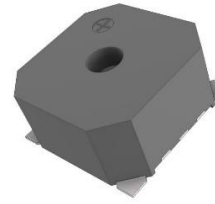




PUIaudio



Data Sheet

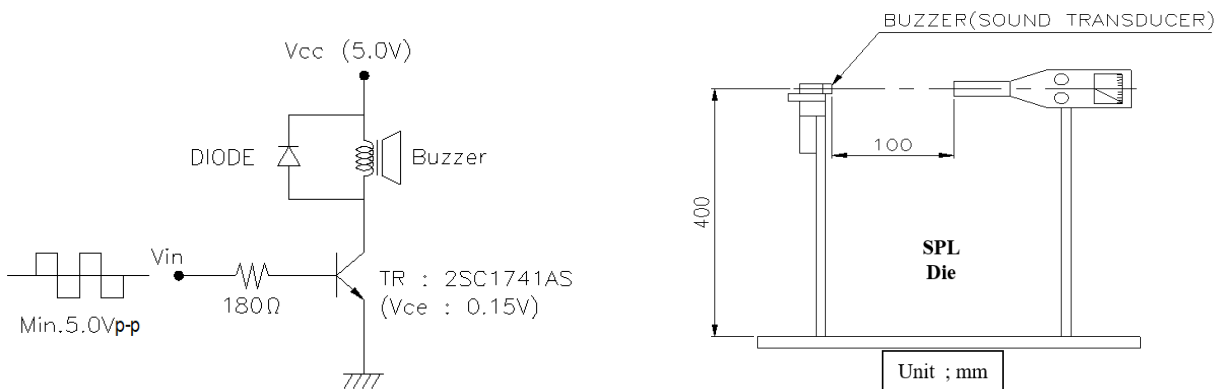
SMT-0830-T-R

Specifications

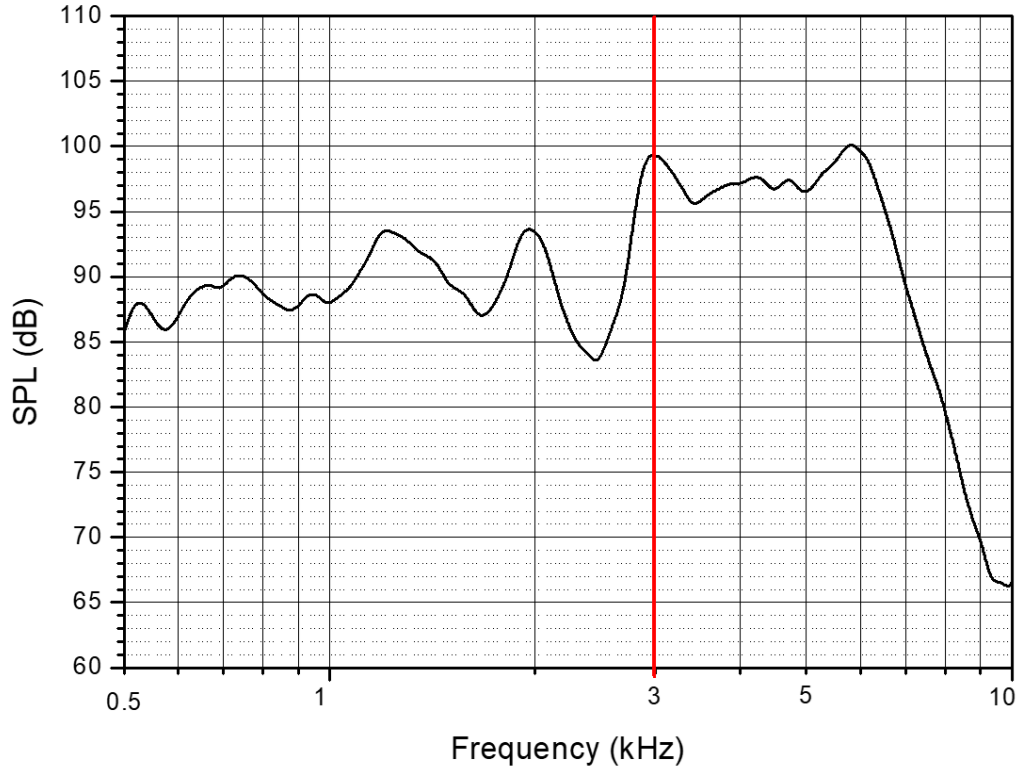
Parameters	Values	Units
Rated Voltage	3.6	V0-pk
Operating Voltage Range	2.5 ~ 4.5	V0-pk
Current Draw at Rated Voltage	90	mA
Coil Resistance	16 ± 2.4	Ohms
Minimum SPL @ 10cm	90	dBA
Resonant Frequency	3000 ± 500	Hz
Housing Material	LCP	-
Terminal Material	Sn plated Phosphor Bronze	-
Weight	.45	Grams
Acceptable Soldering Methods	Reflow/Manual Solder	See following pages
Environmental Compliances	RoHS/REACH	-
Storage Temperature	-40 ~ +85	°C
Operating Temperature	-30 ~ +80	°C

Measurement Method (Temperature: 25±3°C; Relative Humidity: 60% ~ 70%)

Standard Test Fixture (Distance: 10cm, 3.6Vpk, 3000Hz square wave)

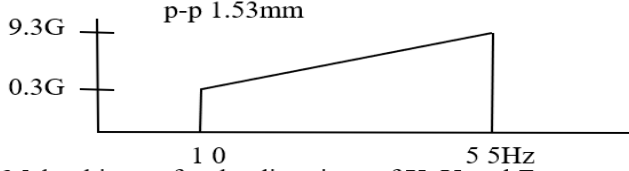


Typical Frequency Response



Reliability Testing

Type of Test	Test Specifications
High Temperature Test	Store at 85C for 96hrs. Then rest at room temperature for 2hrs.
Low Temperature Test	Store at -40C for 96hrs. Then rest at room temperature for 2hrs.
Humidity Test	<p>1 cycle : 12 Hr</p> <p>Make this test for 10 cycles without applying power, then expose to the room temperature for 2 hours.</p>
Temperature Cycle Testing	<p>1 cycle : 90 min</p> <p>Make this test for 5 cycle without applying power, then expose to the room temperature for 2 hours.</p>

<p>Vibration Test</p>	 <p>Make this test for the directions of X, Y and Z. for 2 hours each (total 6 hours). To-and-fro sweep time is 1 minute</p> <p>Dimension of PCB : 60×90 ×1.6t (mm)</p>
<p>Shock Test</p>	<p>If applicable, describe conditions of test.</p>
<p>Drop Test</p>	<p>Fix to PCB with polyester film (wt. 100g) and drop from height of 120cm onto each six surfaces 3 times</p>
<p>Load Test</p>	<p>If applicable, state the conditions of the load test</p>

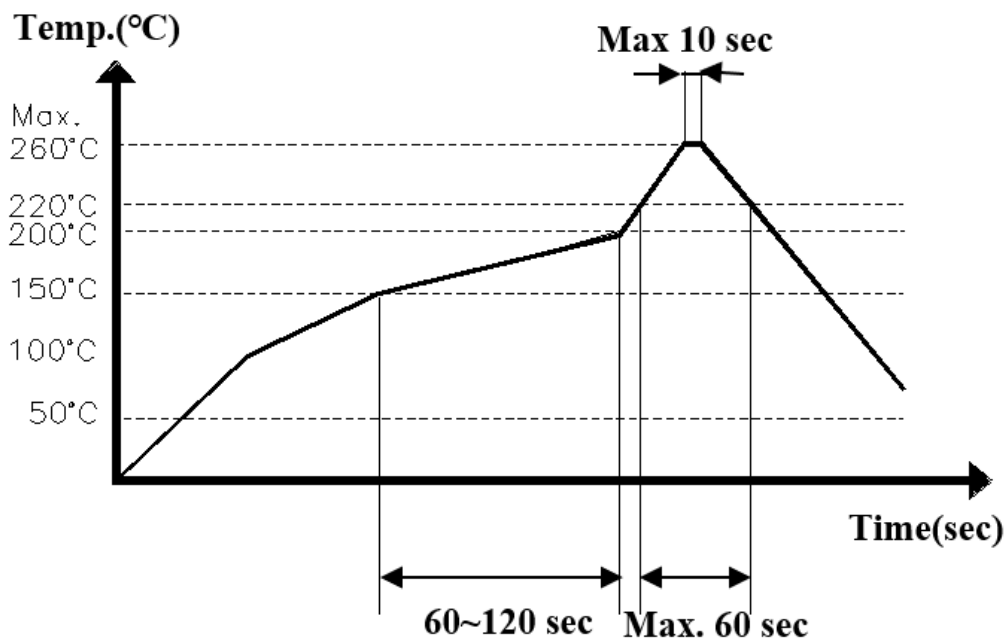
Part shall be within $\pm 5\text{dB}$ after testing.

Reflow Profile

- Recommendable reflow soldering condition is as follows.

Note 1; It is requested that reflow soldering should be executed after heat of product goes down to normal temperature.

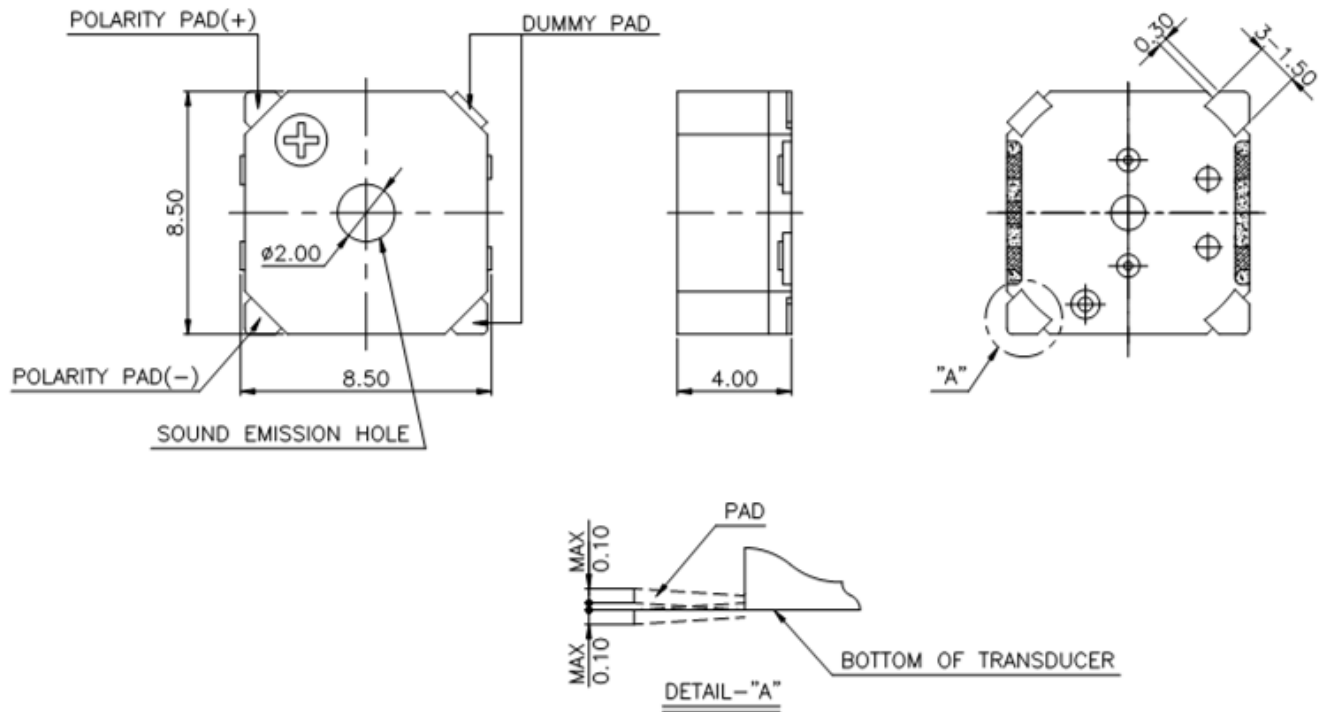
Note 2; Peak reflow temperature of 260°C, with a maximum duration of 60 sec. between 220°C and 260°C



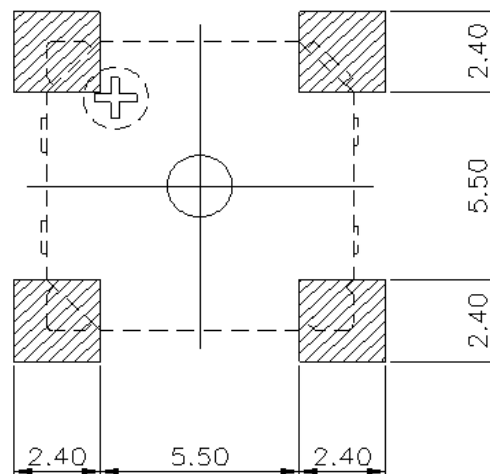
* Reflow profile of lead-free

Manual Solder – Iron Temperature 350°C, Solder time 2-3 seconds per terminal.

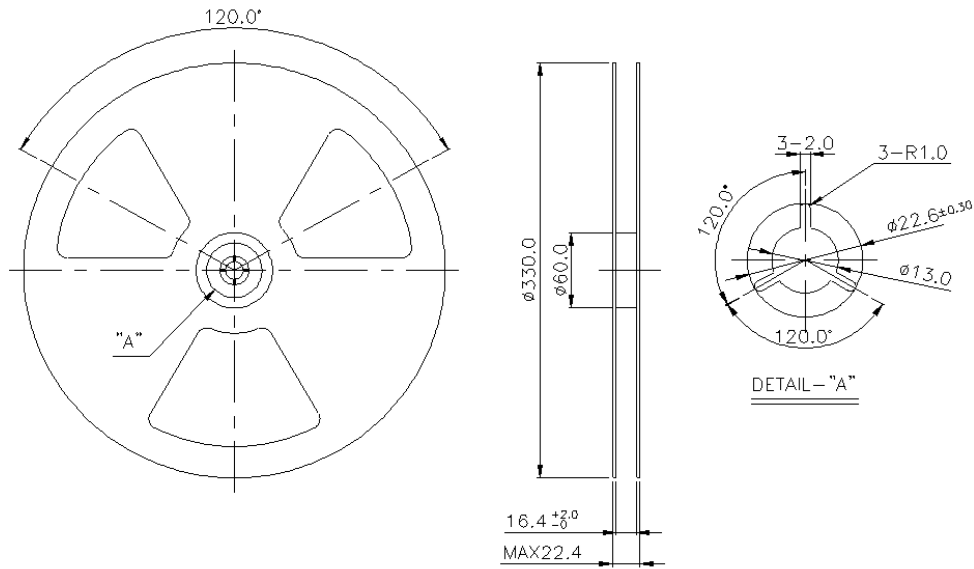
Dimensions (Tolerances $\pm 0.2\text{mm}$ unless otherwise specified)



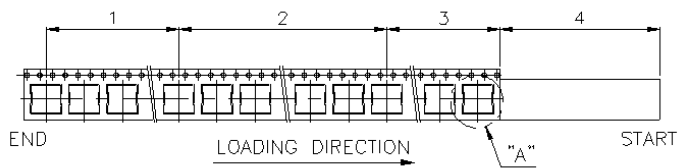
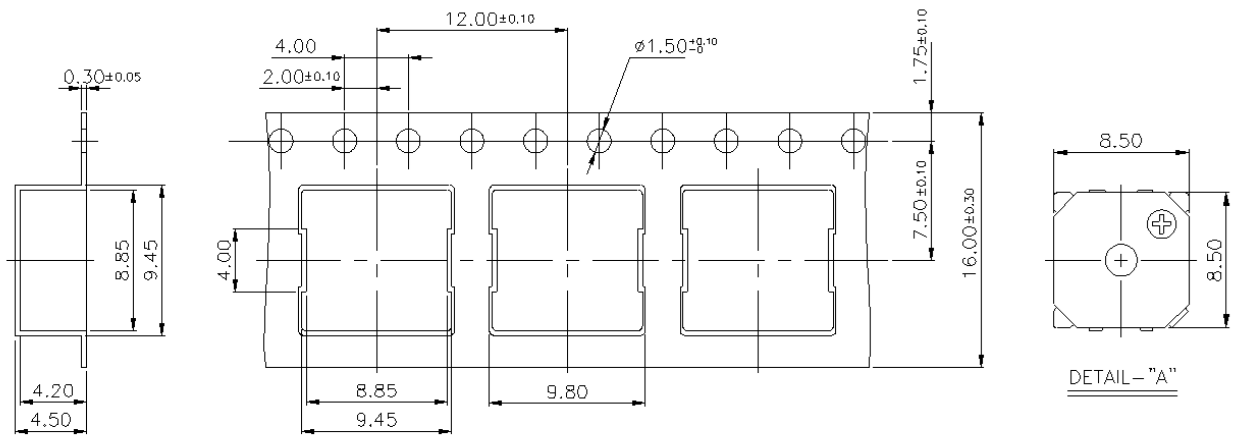
Recommended Land Pattern



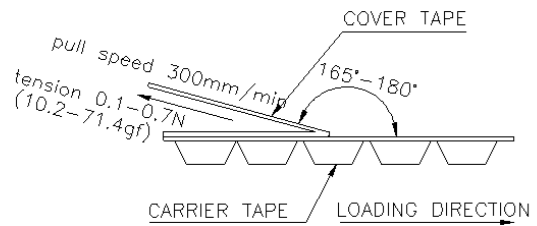
Packaging

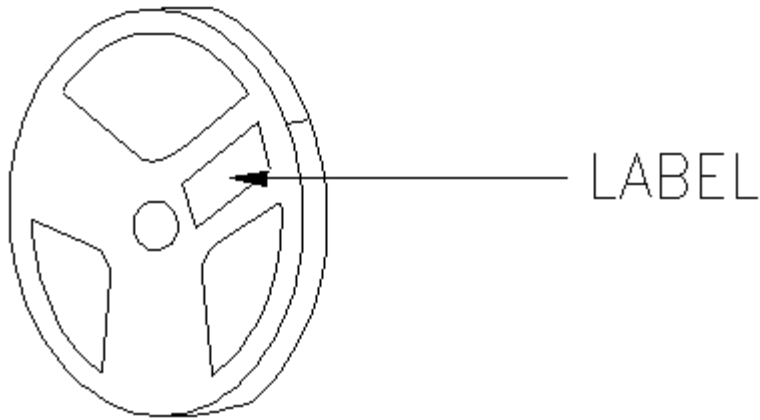


Tolerance ; ±0.2	Unit ; mm
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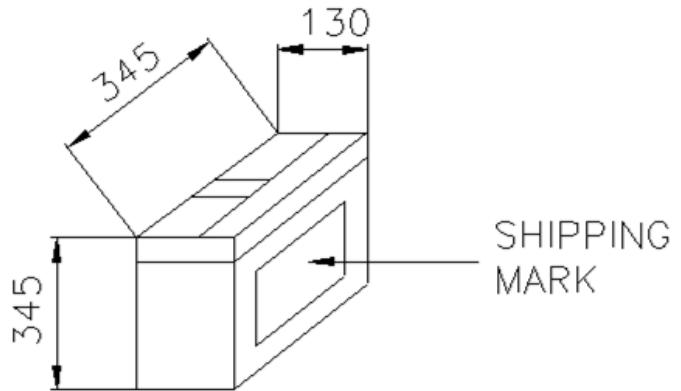
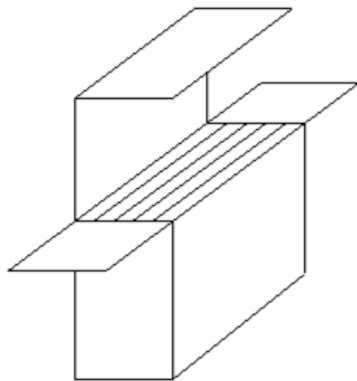
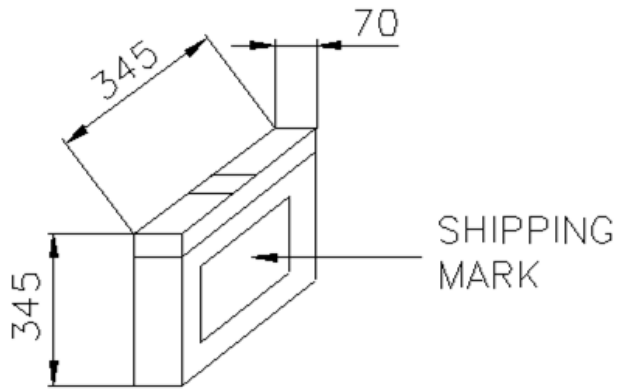
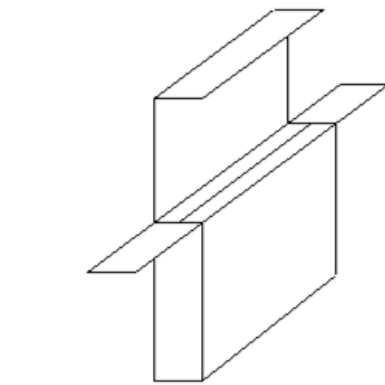
1. BARE EMBOSS AREA : 400mm OVER(35PCS OVER)
2. CHIP MOUNT AREA : 1,000PCS
3. BARE EMBOSS AREA : 400mmOVER(35PCS OVER)
4. LEADER AREA : 100mm OVER





1000pcs Reel

2 Reels per box, 5 boxes per Mstr Carton



Specifications Revisions

Revision	Description	Date	Approved
-	RELEASED FROM ENGINEERING	06/17/2008	
A	REVISED INTERNAL SOLDER CONNECTIONS	09/02/2008	
B	ADDED NOTE #4	09/17/2008	
C	Revised Specification Parameters, Land Pattern Image	02/07/2024	M.L.

Note:

1. Unless otherwise specified:
 - A. All dimensions are in millimeters.
 - B. Default tolerances are $\pm 0.5\text{mm}$ and angles are $\pm 3^\circ$.
2. Specifications subject to change or withdrawal without notice.
3. ROHS/REACH Compliant.
4. Sealed Lower Housing.